



Embedded Fanless System



TASK

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Back Panel Motherboard I/O



Blue-marked area is for extra functions

Back Panel Expansion I/O Possibilities & more



Front / Back Including, but not limited to these functions

Motherboard		3i610DW	3i170DW
System Dimension(WxDxH)		210W x 125D x 77H mm	210W x 125D x 77H mm
Weight(Incl.M/B)		1.9 kg	1.9 kg
CPU		Intel Skylake-U / Kaby Lake-U i7, i5, i3 Celeron CPU	Intel Skylake-S / Kaby Lake-S i7, i5, i3 Celeron CPU
Chipset			Intel® Q170
Memory	Type / Capacity	DDR4 2133 MT/s, Max up to 32GB	DDR4 2133 MT/s, Max up to 16GB
	SO-DIMM	2	1
	On board memory	N/A	N/A
SSD storage	mSATA	YES	YES
HDD Space		mSATA / 2.5" HDD	mSATA / 2.5" HDD
VGA / DP		N/A	VGA
HDMI / DVI		2 x HDMI	1 x HDMI
USB		4 x USB 3.0	2 x USB 3.0, 2 x USB 2.0
COM		2	2
Mini-PCle		1 x Full size Mini card for PCIe / mSATA / USB 1 x Full size Mini card for PCIe / USB	1 x Full size Mini card for PCIe / mSATA / USB 1 x Full size Mini card for PCIe / USB
SIM Card Holder		1 x Nano SIM sockt	1
GPIO		4DI / 4DO (Optional)	8DI / 8DO (Optional)
Ethernet		5 x Intel GbE	5 x Intel GbE
Power Input		Wide Range DC IN +9V~36V	Wide Range DC IN +9V~36V
Expansion		3G / 4G, GPS, Bluetooth, WI-FI	3G / 4G, GPS, Bluetooth, WI-FI
Optional MB		3i170DW	3i610DW
Operating Temp		-20°C~70°C for mSATA / SSD HDD	-20°C~70°C for mSATA / SSD HDD
Operating Humidity		5~95% @ 60°C, non-condensing	5~95% @ 60°C, non-condensing